-	Туре	L #	Hits	Search Text	DBs	
1	BRS	L1	0	29/25.9	USPAT	
2	BRS	L3	0	1 and modular.ti.	USPAT	
3	BRS	L4	0	1 and modular	USPAT	
4	BRS	L5	1	2 and modular.ti.	USPAT	
5	BRS	L6	2	modular adj substrate.ti.	USPAT	
6	BRS	L7	0	6 adj processing.ti.	USPAT	
7	BRS	L9	1	8 adj processing	USPAT	
8	BRS	L10	0	8 adj processes	USPAT	
9	BRS	L11	0	8 adj processive	USPAT	
10	BRS	L12	1	8 adj process\$3	USPAT	
11	BRS	L13	1	12 adj system	USPAT	
12	BRS	L14	3463	processing adj chamber	USPAT	
13	BRS	L15	0	14 adj load adj clock	USPAT	
14	BRS	L16	28	14 adj load	USPAT	
15	BRS	L17	157934	16 adk clock	USPAT	
16	BRS	L18	0	16 adj clock\$3	USPAT	
17	BRS	L19	0	16 adj clock	USPAT	
18	BRS	L21	3	16 and clock	USPAT	
19	BRS	L22	22	modular adj substrate	USPAT	
20	BRS	L23	189	29/25	USPAT	
21	BRS	L25	206	438/680	USPAT	
22	IS&R	L27	2	(("5494494") or ("5478780")).PN.	USPAT	
23	BRS	L28	1	5535306	USPAT	
24	BRS	L30	198	4951601	USPAT	
25	BRS	L33	10	5478780	USPAT	
26	BRS	L34	10	5494494	USPAT	

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	Туре	L #	Hits	Search Text	DBs
27	BRS	L35	16	5288379	USPAT

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		Document ID	Title A	Current OR
i	1	US 5280983 A	Semiconductor processing system with robotic autoloader and load lock	294/119.1
	2	US 5224809 A	Semiconductor processing system with robotic autoloader and load lock	414/217
	3	US 4911597 A	Semiconductor processing system with robotic autoloader and load lock	414/217

	Document ID	Title A	Current OR
1	US 5838121 A	Dual blade robot	318/45
2	US 5911834 A	Gas delivery system	134/1.3
3	US 5505779 A	method for	118/719
4	US 5494494 A	nrocessing substrates Integrated module multi-chamber CVD processing system and its method for	438/680
5	US 5905302 A	processing substrates Loadlock cassette with wafer support rails	257/678
6	US 5514257 A	Method for forming Ti-tin laminates	204/192.17
7	US 5288379 A	Multi-chamber integrated process system	204/192.12
8	US 5628828 A	Processing method and equipment for processing a semiconductor device  having holder/carrier with flattened surface	118/719
9	US 5844195 A	,	219/121.43
10	US 5902088 A	Single loadlock chamber with wafer cooling function	414/217
11	US 5961269 A	Three chamber load lock apparatus	414/221
12	US 5855681 A	Ultra high throughput wafer vacuum processing system	118/719

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